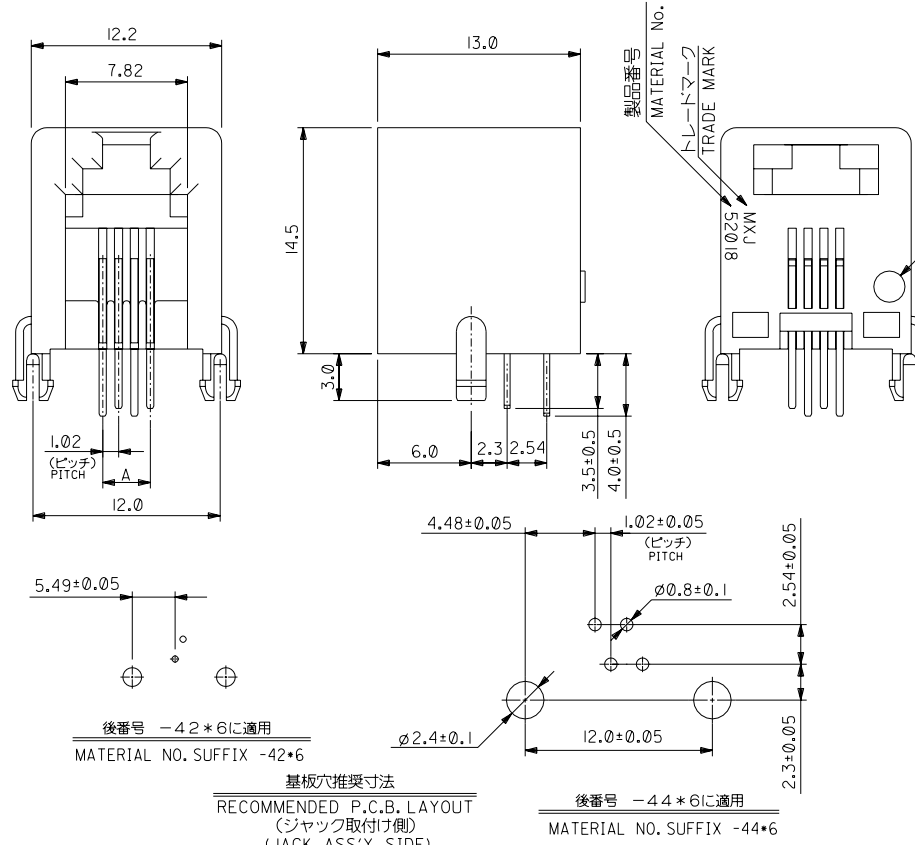


DWG. NO. SD-52018-002
 OSA LEI 110.315520 8C4.DGN
 DO NOT SCALE DRAWING



- 注) NOTES
- 材質 MATERIAL
 ハウジング: ガラス入りポリエステル UL94V-0
 HSG.: POLYESTER G.F.15% UL94V-0
 ターミナル: リン青銅
 TERM.: PHOSPHOR BRONZE
 - メッキ仕様 PLATING
 接点部: 金メッキ, 表参照
 CONTACT AREA: GOLD PER TABLE
 半田付け部: 錫メッキ 1.0µmMIN.
 SOLDER AREA: TIN 1.0 MICROMETER MINIMUM.
 下地メッキ: ニッケルメッキ 1.0µmMIN.
 UNDERPLATE: NICKEL 1.0 MICROMETER MINIMUM.
 - 推奨基板厚: t=1.6±0.05
 RECOMMENDED P.C.B. THICKNESS: 1.6±0.05
- ④ 金メッキ厚標示
 COLOR CODING TO INDICATE GOLD PLATING
 黄色: 0.1µmMIN.
 YELLOW: 0.1 MICROMETER MINIMUM.
 緑色: 0.38µmMIN.
 GREEN: 0.38 MICROMETER MINIMUM.
 オレンジ色: 0.76µmMIN.
 ORANGE: 0.76 MICROMETER MINIMUM.
 無色: 1.27µmMIN.
 UNMARKED: 1.27 MICROMETER MINIMUM.
- ハウジングの色は、グレイ。
 HOUSING COLOR IS GRAY.
 - 本製品は52018-4**5の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 52018-4**5.

4	4	3.05	1.27	52018-4446
			0.76	↑ -4436
			0.38	-4426
4	2	1.02	0.1	↓ -4416
			1.27	52018-4246

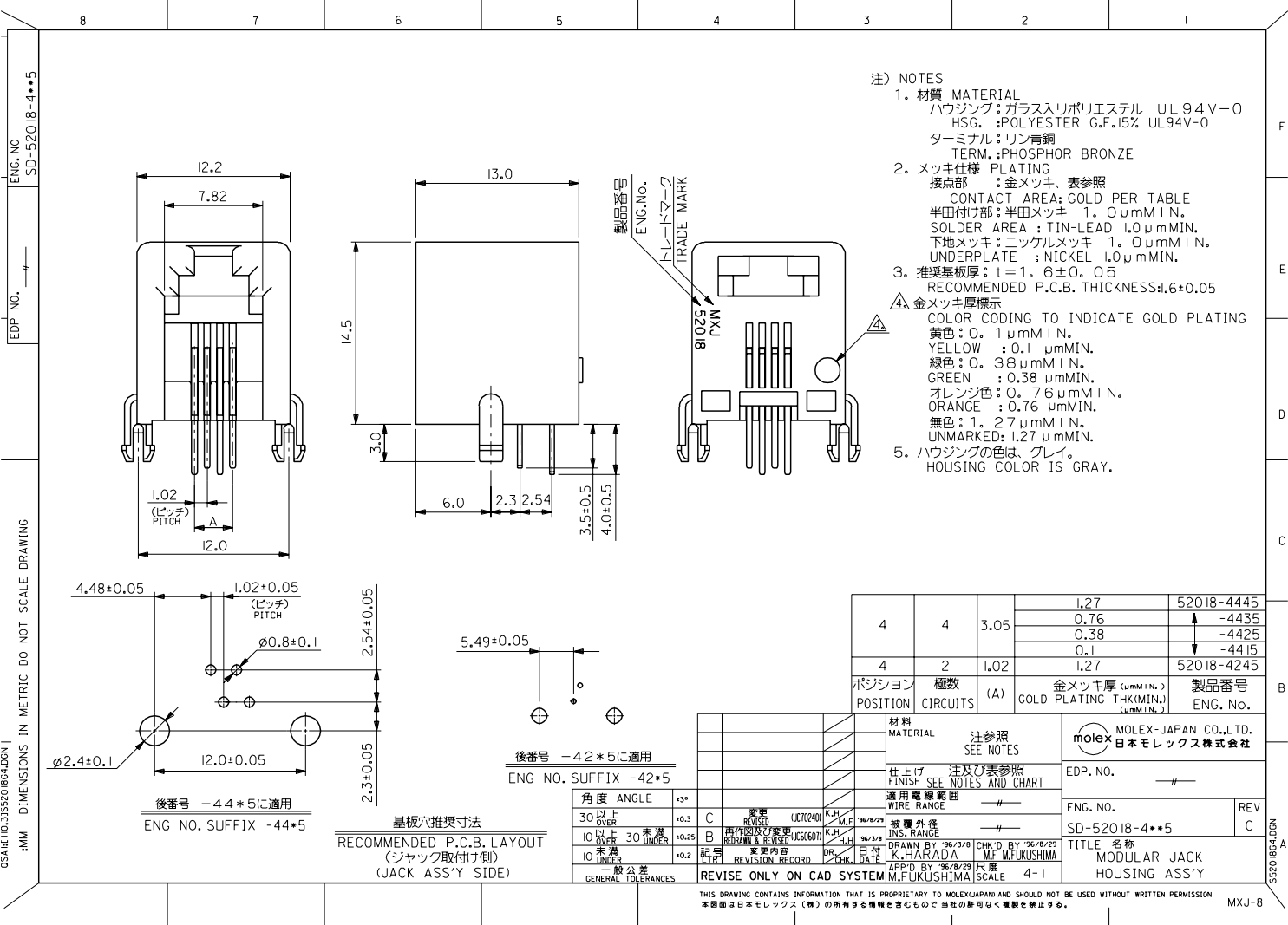
ポジション POSITION	極数 CIRCUITS	(A)	金メッキ厚 (µmMIN.) GOLD PLATING THK(MIN.)	製品番号 MATERIAL NO.
			(µmMIN.)	

基板穴推奨寸法
 RECOMMENDED P.C.B. LAYOUT
 (ジャック取付け側)
 後番号 -42*6に適用 MATERIAL NO. SUFFIX -42*6
 後番号 -44*6に適用 MATERIAL NO. SUFFIX -44*6

E31 NO. DRWN: CH'K: APPR: E32 NO. DRWN: CH'K: APPR: E33 NO. DRWN: CH'K: APPR: E34 NO. DRWN: CH'K: APPR: E35 NO. DRWN: CH'K: APPR: E36 NO. DRWN: CH'K: APPR: E37 NO. DRWN: CH'K: APPR: E38 NO. DRWN: CH'K: APPR: E39 NO. DRWN: CH'K: APPR: E40 NO. DRWN: CH'K: APPR: E41 NO. DRWN: CH'K: APPR: E42 NO. DRWN: CH'K: APPR: E43 NO. DRWN: CH'K: APPR: E44 NO. DRWN: CH'K: APPR: E45 NO. DRWN: CH'K: APPR: E46 NO. DRWN: CH'K: APPR: E47 NO. DRWN: CH'K: APPR: E48 NO. DRWN: CH'K: APPR: E49 NO. DRWN: CH'K: APPR: E50 NO. DRWN: CH'K: APPR: E51 NO. DRWN: CH'K: APPR: E52 NO. DRWN: CH'K: APPR: E53 NO. DRWN: CH'K: APPR: E54 NO. DRWN: CH'K: APPR: E55 NO. DRWN: CH'K: APPR: E56 NO. DRWN: CH'K: APPR: E57 NO. DRWN: CH'K: APPR: E58 NO. DRWN: CH'K: APPR: E59 NO. DRWN: CH'K: APPR: E60 NO. DRWN: CH'K: APPR: E61 NO. DRWN: CH'K: APPR: E62 NO. DRWN: CH'K: APPR: E63 NO. DRWN: CH'K: APPR: E64 NO. DRWN: CH'K: APPR: E65 NO. DRWN: CH'K: APPR: E66 NO. DRWN: CH'K: APPR: E67 NO. DRWN: CH'K: APPR: E68 NO. DRWN: CH'K: APPR: E69 NO. DRWN: CH'K: APPR: E70 NO. DRWN: CH'K: APPR: E71 NO. DRWN: CH'K: APPR: E72 NO. DRWN: CH'K: APPR: E73 NO. DRWN: CH'K: APPR: E74 NO. DRWN: CH'K: APPR: E75 NO. DRWN: CH'K: APPR: E76 NO. DRWN: CH'K: APPR: E77 NO. DRWN: CH'K: APPR: E78 NO. DRWN: CH'K: APPR: E79 NO. DRWN: CH'K: APPR: E80 NO. DRWN: CH'K: APPR: E81 NO. DRWN: CH'K: APPR: E82 NO. DRWN: CH'K: APPR: E83 NO. DRWN: CH'K: APPR: E84 NO. DRWN: CH'K: APPR: E85 NO. DRWN: CH'K: APPR: E86 NO. DRWN: CH'K: APPR: E87 NO. DRWN: CH'K: APPR: E88 NO. DRWN: CH'K: APPR: E89 NO. DRWN: CH'K: APPR: E90 NO. DRWN: CH'K: APPR: E91 NO. DRWN: CH'K: APPR: E92 NO. DRWN: CH'K: APPR: E93 NO. DRWN: CH'K: APPR: E94 NO. DRWN: CH'K: APPR: E95 NO. DRWN: CH'K: APPR: E96 NO. DRWN: CH'K: APPR: E97 NO. DRWN: CH'K: APPR: E98 NO. DRWN: CH'K: APPR: E99 NO. DRWN: CH'K: APPR: E00 NO. DRWN: CH'K: APPR:	新規格作成 RELEASED 020004-4214 DRWN: M.NAGATA 04/05/13 CH'K: K.TOJO 04/05/13 APPR: M.SASAO 04/05/13	MATERIAL 材料 注参照 SEE NOTES FINISH 仕上げ 注及び表参照 SEE NOTES AND CHART WIRE RANGE 適用電線範囲 INS. RANGE 被覆外径	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未満 +0.2 10 OVER 以上 30 UNDER 未満 +0.25 30 OVER 以上 +0.3 ANGLE 角度 ±3°	SCALE 4:1 DESIGN UNITS mm INCH DRAWN BY & DATE M.NAGATA 04/05/13 CHECKED BY & DATE K.TOJO 04/05/13 APPROVED BY & DATE M.SASAO 04/05/13 CAD FILENAME SD-52018-002.S01	DIMENSIONS: mm INCH mm ONLY DIMENSIONAL ANGLE PROJECTION TITLE: MODULAR JACK HOUSING ASS'Y -LEAD FREE- MOLEX INCORPORATED	SHT 1 OF 1 REV B SIZE B
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MODEL NO. 52018-4**6	DIMENSIONS: mm INCH mm ONLY	SHT 1 OF 1
CAD FILENAME SD-52018-002.S01	MATERIAL NO. SEE CHART	DRAWING NO. SD-52018-002
DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		

EN-02J(097) MXJ-54



- 注) NOTES
1. 材質 MATERIAL
ハウジング: ガラス入りポリエステル UL94V-0
HSG.: POLYESTER G.F.15% UL94V-0
ターミナル: リン青銅
TERM.: PHOSPHOR BRONZE
 2. メッキ仕様 PLATING
接点部: 金メッキ、表参照
CONTACT AREA: GOLD PER TABLE
半田付け部: 半田メッキ 1.0 μmMIN.
SOLDER AREA: TIN-LEAD 1.0 μmMIN.
下地メッキ: ニッケルメッキ 1.0 μmMIN.
UNDERPLATE: NICKEL 1.0 μmMIN.
 3. 推奨基板厚: t=1.6±0.05
RECOMMENDED P.C.B. THICKNESS: 1.6±0.05
 4. 金メッキ厚標示
COLOR CODING TO INDICATE GOLD PLATING
黄色: 0.1 μmMIN.
YELLOW: 0.1 μmMIN.
緑色: 0.38 μmMIN.
GREEN: 0.38 μmMIN.
オレンジ色: 0.76 μmMIN.
ORANGE: 0.76 μmMIN.
無色: 1.27 μmMIN.
UNMARKED: 1.27 μmMIN.
 5. ハウジングの色は、グレイ。
HOUSING COLOR IS GRAY.

4	4	3.05	1.27	52018-4445
			0.76	-4435
			0.38	-4425
			0.1	-4415
4	2	1.02	1.27	52018-4245

POSITION CIRCUITS (A) GOLD PLATING THK(MIN.) (μmMIN.) 製品番号 ENG. No.

材料 MATERIAL	注参照 SEE NOTES	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH	注及び表参照 SEE NOTES AND CHART	EDP. NO.	—
適用電線範囲 WIRE RANGE	—	ENG. NO.	SD-52018-4**5
被覆外径 INS. RANGE	—	REV	C
DRAWN BY K.HARADA	DATE	TITLE 名称 MODULAR JACK HOUSING ASS'Y	
CHK'D BY M.FUKUSHIMA	DATE	SCALE 4-1	

角度 ANGLE	+30		
30以上 OVER	+0.3	C	変更 REVISD (JCT0240) K.H.F. 96/8/29
10以上 30未満 UNDER	+0.25	B	挿入部及び変更 REVISION (JCS0607) K.H.F. 96/8/29
10未満 UNDER	+0.2	A	記号 変更内容 DR. 日付
一般公差 GENERAL TOLERANCES			REVISION RECORD DR. CHK. DATE

REVISE ONLY ON CAD SYSTEM

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本図面は日本モレックス(株)の所有する情報を含むもので 当社の許可なく複製を禁止する。 MXJ-B

ENG. NO. SD-52018-4**5
EDP. NO. —
DIMENSIONS IN METRIC DO NOT SCALE DRAWING
OS4H110.3J55201804.D0N1

F
E
D
C
B
A